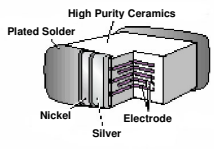
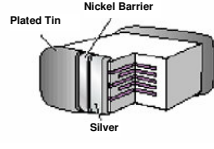
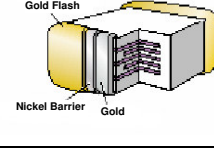
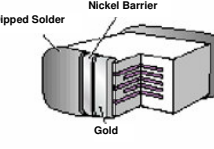
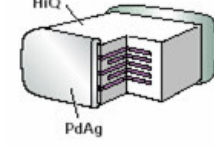
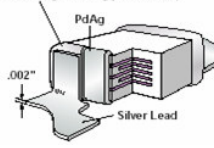


Dielectric Laboratories Inc. offers a broad range of Multilayer Capacitor products. Our products include C04, C06, C08, C11, C17, C22 and C40 High Q capacitors. Additionally we offer a unique range of broadband blocking capacitors. The terminations styles available are suitable for a wide array of applications.

Configuration	Part Number Code	Typical Metallization	Application	Metallization Layer
	U	<ul style="list-style-type: none"> Ag Termination Ni Barrier Layer Sn-Pb Plated Solder 	<ul style="list-style-type: none"> High Volume Solder Assembly SMD-SMT Hand Soldering 	Ni – 100-250 μ " Sn-Pb – 100-150 μ " 90Sn • 10Pb (solder melting temp 213°C)
	Z	<ul style="list-style-type: none"> Lead Free Ag Termination Ni Barrier Layer Sn Plated Solder 	<ul style="list-style-type: none"> High Volume Solder Assembly SMD-SMT Hand Soldering 	Ni – 200-250 μ " Sn – 200 μ " (solder melting temp 232°C)
	S	<ul style="list-style-type: none"> Au Termination Ni Barrier Layer Gold 	<ul style="list-style-type: none"> Epoxy Mounting Specialty Solder Applications Lead-Free Solder Applications 	Ni – 100-250 μ " Gold – 5 μ "
	T	<ul style="list-style-type: none"> Au Termination Ni Barrier Layer Sn Plated Solder Hot Solder Dip 	<ul style="list-style-type: none"> Hand Soldering Solder Assembly 	Ni – 100-250 μ " Sn62 – 62 Sn • 36 Pb • 2 Ag (solder melting temp 179°C)
	P	<ul style="list-style-type: none"> Pd - Ag Termination 	<ul style="list-style-type: none"> Non-Magnetic Applications Hand Soldering Lead-Free Solder Applications SMD-SMT 	4:1 Silver:Palladium Ratio
	A	<ul style="list-style-type: none"> Pd - Ag Termination HMP Solder Silver Ribbon Lead 	<ul style="list-style-type: none"> Hand Soldering 	4:1 Silver:Palladium Ratio 5 Sn • 93.5 Pb • 1.5 Ag (solder melting temp 296°C)